Kokomo Semiconductor

FBT250 Test Die

The Kokomo Semiconductor FBT250 test chip is designed with I/O pads on 18 mil (457.2 micron) pitch located on the peripheral of the die. The 0.25-inch by 0.25-inch FBT250 die contains 48 pads giving 24 daisy chain pairs.

IC Fab Information

- Wafer size: 5-inch (125 mm)
- Die thickness: 600-650 microns
- Metal thickness: 17k angstroms
- Metal composition: Al/Cu/Si (98/1/1)
- Passivation thickness: 10k angstroms
- Passivation type: Nitride

Die Sizes Available

- .250” x .250”

Options Available

1) Five-inch wafer, no bumps, nitride passivation, 102-micron circular passivation openings (diagram 1)

2) Five-inch wafer, FOC bump, 63Sn/37Pb solder, UBM diameter – 178 microns, bump height –140 microns (diagram 3)

Note: Lead Free solder composition available upon request.
Diagram 1

All Units are in Microns

Diagram 3

= Solder Diameter

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Daisy Chain Dimensional Information

All Units are Microns.
The test die offered on this web site are to be used to characterize assembly processes and materials. Applying the data from the test die to a functional system is the responsibility of the user. Kokomo Semiconductor makes no warranty, express or implied including the implied warranties of merchantability and fitness for a particular purpose, that the user’s system designed using that data will perform as intended by the user.